Features

- IEC61000-4-2 (ESD) ±30KV(Air), ±30KV(contact)
  IEC61000-4-4 (EFT) 40A (5/50ns)
- 350 Watts Peak Pulse Power per (tp=8/20us)
- Protects one I/O line (bidirectional)
- Working voltages : 5V
- Low leakage current

Applications

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digal Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Networking and Telecom
- Serial and Parallel Ports.
- Peripherals

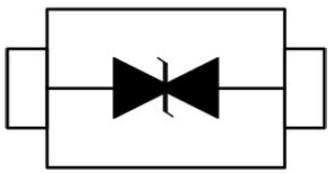
Mechanical Characteristics

- SOD-323FL package
- Flammability Rating: UL 94V-0
- Packaging: Tape and Reel
- High temperature soldering guaranted:260℃/10s
- Reel size: 7 inch

Description

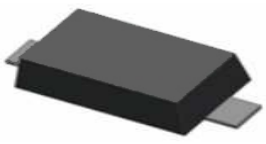
The S0501LE Series is designed for applications requiring transient overvoltage protection capability. They are intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipmentand other applications. These devices are ideal for situations where board space is at a premium.
This series has been specifically designed to protect sensitive components which are connected to power data andtransmissionlines from overvoltagecaused by ESD(electrostatic discharge), CDE (Cable Discharge Events),and EFT (electrical fast transients).

Pin Congfiguration



SOD-323FL
(Top View)

Package Outline



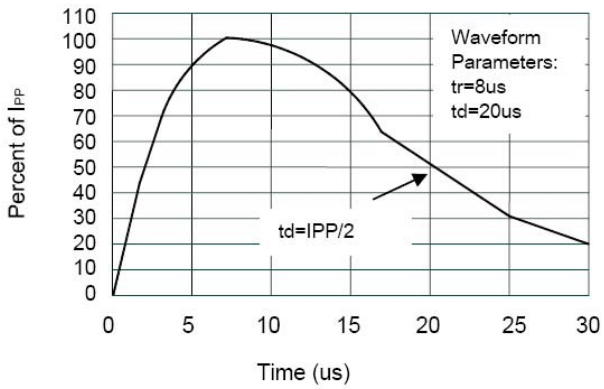
SOD-323 Flat LEAD

Absolute Maximum Rating

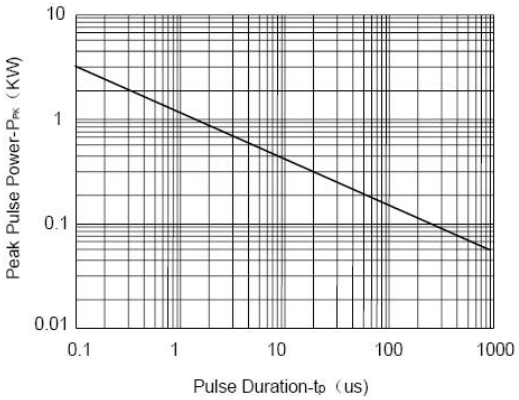
Symbol	Parameter	Value	Units
V_{ESD}	ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	±30 ±30	kV
P_{PP}	Peak Pulse Power (8/20μs)	350	W
T_{OPT}	Operating Temperature	-55/+150	°C
T_{STG}	Storage Temperature	-55/+150	°C
T_L	Lead Soldering Temperature	260 (10 sec.)	°C

Electrical Characteristics (T = 25°C)

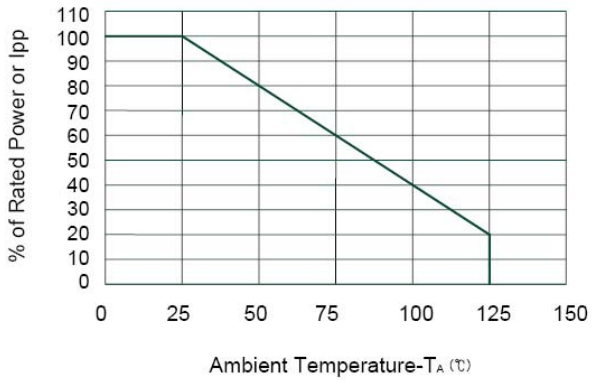
PART NUMBER	V_{RWM} (V) (max.)	V_B (V) (min.)	I_T (mA)	V_C@5A (V) (max.)	V_C (V) (max.)	(@A)	I_R (uA) (max.)	C_T (pF) (max.)	DEVICE MARKING
S0501LE	5	6	1	9.8	14.5	17	10	200	2B



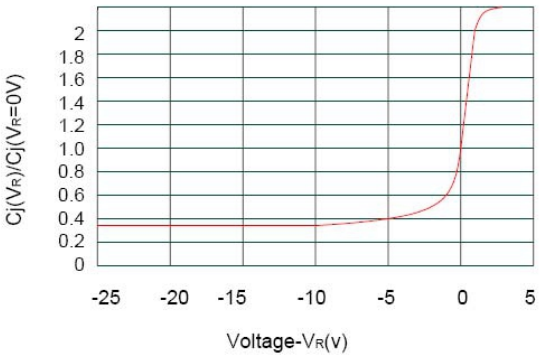
Pulse Waveform



Non-Repetitive Peak Pulse Power vs. Pulse Time



Power Derating Curve

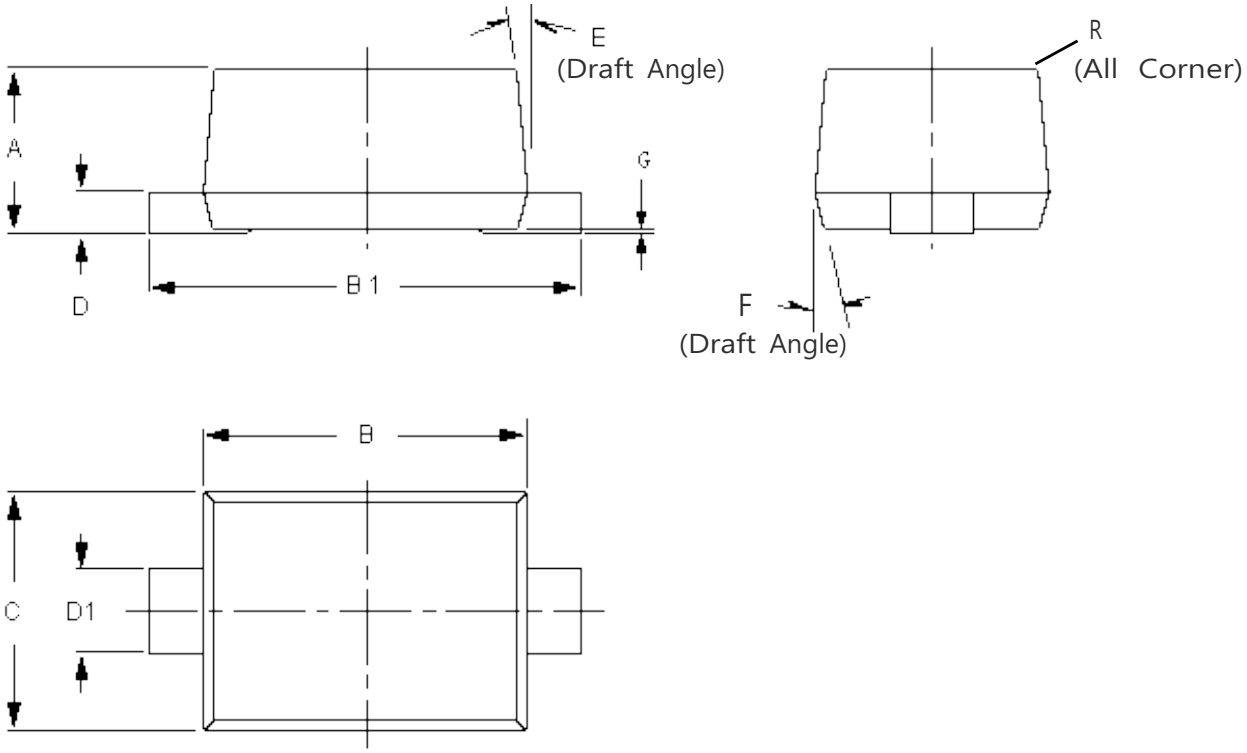


Junction Capacitance vs. Reverse Voltage

Document ID : DS-22V10
Revised Date : 2016/08/30
Revision : C

Package Outline Demensions

- SOD323FL package



Symbol	Dim in mm		
	Min	Nom	Max
A	0.800	0.700	0.900
B	1.650	1.700	1.750
B1	2.550	2.600	2.750
C	1.250	1.300	1.350
D	0.090	0.100	0.110
D1	0.280	0.300	0.320
E	7°	8°	9°
F	9°	10°	11°
G	0.000	-	0.020
R	0.020	-	0.050

Mold Surface roughness: < 4um

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